

3.3 V LVDS, 1-Bit, **High-Speed Differential Driver**

FIN1017

SOIC8 CASE 751EB

General Description

This single driver is designed for high-speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTL signal levels to LVDS levels with a typical differential output swing of 350 mV, which provides low EMI at ultra-low power dissipation even at high frequencies. This device is ideal for high-speed transfer of clock or data.

The FIN1017 can be paired with any other LVDS receiver.

Features

- Greater than 600 Mbs Data Rate
- 3.3 V Power Supply Operation
- 0.5 ns Maximum Differential Pulse Skew
- 1.5 ns Maximum Propagation Delay
- Low Power Dissipation
- Power-Off Protection
- Meets or Exceeds the TIA/EIA-644 LVDS Standard
- Flow-Through Pinout Simplifies PCB Layout
- 8-Lead SOIC Package Saves Space
- This Device is Pb–Free, Halide Free and is RoHS Compliant

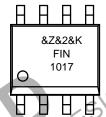
PIN CONFIGURATION

Pin# SOIC	Name	Description
2	DIN	LVTTL Data Input
7	D _{OUT+}	Non-inverting Driver Output
8 5	D _{OUT} Inverting Driver Output	
1	V _{CC}	Power Supply
4	GND	Ground
3, 5, 6	NC	No Connect

FUNCTIONAL TABLE

Input	Outputs		
D _{IN}	D _{OUT+} D _{OUT-}		
LOW	LOW	HIGH	
HIGH	HIGH	LOW	
OPEN	LOW	HIGH	

MARKING DIAGRAM

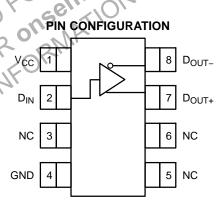


Assembly Plant Code

= 2-Digit Date Code

= 2-Digits Lot Run Traceability Code

FIN1017 = Specific Device Code



ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet

FIN1017

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	-0.5	+4.6	V
D _{IN}	DC Input Voltage	-0.5	+6.0	V
D _{OUT}	DC Output Voltage	-0.5	+4.7	V
I _{OSD}	Driver Short-Circuit Current, Continuous	-	10	mA
T _{STG}	Storage Temperature Range	-65	+150	°C
T_J	Max Junction Temperature	-	+150	°C
TL	Lead Temperature (Soldering, 10 Seconds)	-	+260	°C
ESD	Human Body Model, JESD22-A114	-	6500	V
	Bus Pins D _{OUT+} /D _{OUT-} to GND	-	10500	
	Machine Model, JESD22-A115	-	350	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min Max Unit	t
V _{CC}	Supply Voltage	3.0 V	
V _{IN}	Input Voltage	0 V _{CC} V	
T _A	Operating Temperature	-40 +85 °C	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (Over–supply voltage and operating temperature ranges, unless otherwise specified. All typical values are at $T_A = 25$ °C and with $V_{CC} = 3.3$ V.)

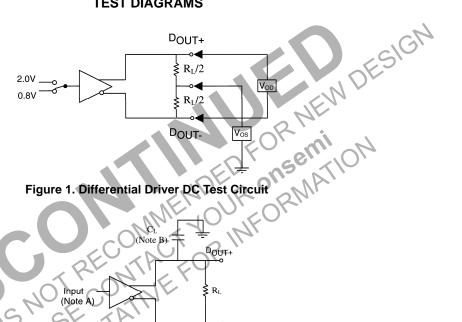
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{OD}	Output Differential Voltage	R_L = 100 Ω, See Figure 1	250	350	450	mV
ΔV_{OD}	VOD Magnitude Change from Differential LOW-to-HIGH	ATIVE	-	_	25	mV
Vos	Offset Voltage	1	1.125	1.250	1.375	V
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH		-	_	25	mV
I _{OFF}	Power-Off Output Current	V _{CC} = 0 V, V _{OUT} = 0 V or 3.6 V	_	-	±20	mA
los	Short-Circuit Output Current	V _{OUT} = 0 V	_	-	-8	mA
		V _{OD} = 0 V	-	-	±8	
V _{IH}	Input HIGH Voltage		2	-	V _{CC}	V
V _{IL}	Input LOW Voltage		GND	-	0.8	V
I _{IN}	Input Current	V _{IN} = 0 V or V _{CC}	-	-	±20	mA
I _{I(OFF)}	Power-Off Input Current	V _{CC} = 0 V, V _{IN} = 0 V or 3.6 V	_	-	±20	mA
V _{IK}	Input Clamp Voltage	I _{IK} = -18 mA	-1.5	-	_	V
I _{CC}	Power Supply Current	No Load, V _{IN} = 0 V or V _{CC}	_	-	8	mA
		$R_L = 100 \Omega$, $V_{IN} = 0 V$ or V_{CC}	_	_	10	mA
CIN	Input Capacitance		-	4	_	pF
Соит	Output Capacitance		_	6	_	pF

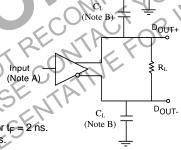
AC ELECTRICAL CHARACTERISTICS (Over-supply voltage and operating temperature ranges, unless otherwise specified. All typical values are at $T_A = 25$ °C and with $V_{CC} = 3.3$ V.)

Symbol	Parameter	Test Conditions	Min	Max	Unit
t _{PLHD}	Differential Propagation Delay, LOW-to-HIGH	$R_L = 100 \Omega$, $CL = 10 pF$, see Figure 2	0.5	1.5	ns
t _{PHLD}	Differential Propagation Delay, HIGH-to-LOW	and Figure 3	0.5	1.5	ns
t _{TLHD}	Differential Output Rise Time (20% to 80%)		0.4	1.0	ns
t _{THLD}	Differential Output Fall Time (80% to 20%)		0.4	1.0	ns
t _{SK(P)}	Pulse Skew t _{PLH} - t _{PHL}		-	0.5	ns
t _{SK(PP)}	Part-to-Part Skew (Note 1)		1	1.0	ns

^{1.} t_{SK(PP)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

TEST DIAGRAMS





NOTES:

A. All input pulses have frequency = 10 MHz, t_R or t_F = 2 ns. B. CL includes all probe and fixture capacitances.

Figure 2. Differential Driver Propagation Delay and Transition Time Test Circuit

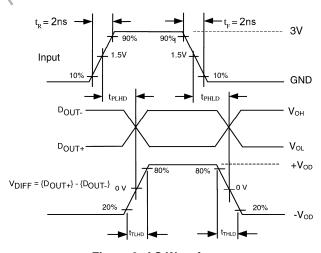


Figure 3. AC Waveforms

FIN1017

TYPICAL PERFORMANCE CHARACTERISTICS

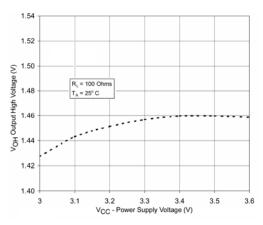


Figure 4. Output High Voltage vs. **Power Supply Voltage**

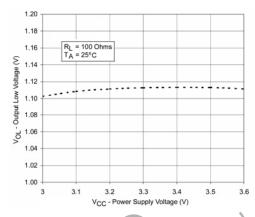
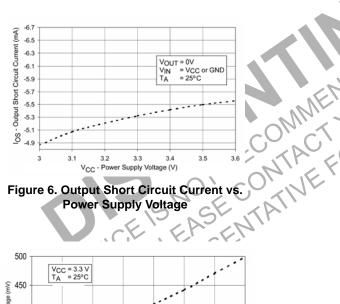


Figure 5. Output Low Voltage vs. **Power Supply Voltage**



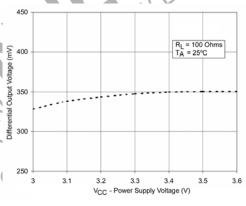


Figure 7. Differential Output Voltage vs. **Power Supply Voltage**

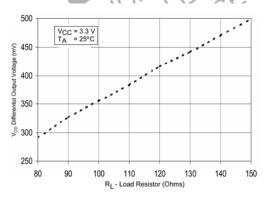


Figure 8. Differential Output Voltage vs. **Load Resistor**

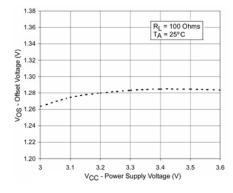


Figure 9. Offset Voltage vs. Power Supply Voltage

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

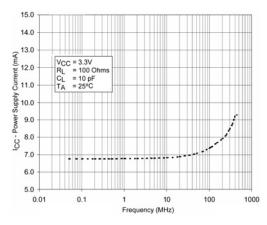


Figure 10. Power Supply Current vs. Frequency

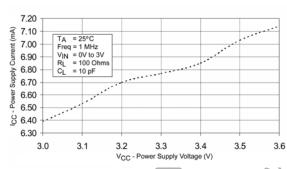
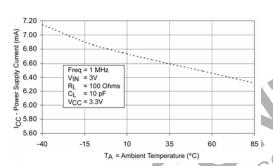


Figure 11. Power Supply Current vs. **Power Supply Voltage**



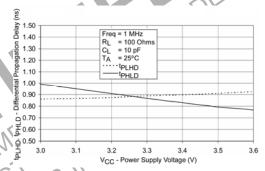


Figure 13. Differential Propagation Delay vs. **Power Supply**

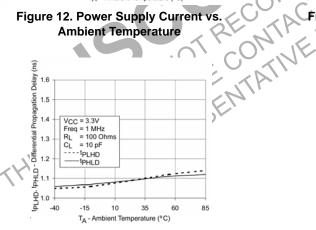


Figure 14. Differential Propagation Delay vs. **Ambient Temperature**

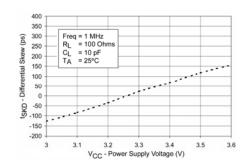
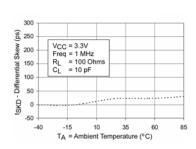


Figure 15. Differential Pulse Skew (t_{PLH} – t_{PHL}) vs. **Power Supply Voltage**

FIN1017

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)



Freq = 1 MHz 1200 1150 1100 1050 =100 Ohms tTLH: tTHL - Transition Time (ps) C_L = 10 pF 1000 950 900 850 800 750 700 650 600 550 500 450 T_A = 25° C ··· t_{TLH} t_{THI} V_{CC} - Power Supply Voltage (V)

Figure 16. Differential Pulse Skew (t_{PLH} - t_{PHL}) vs. **Ambient Temperature**

Figure 17. Transition Time vs. **Power Supply Voltage**

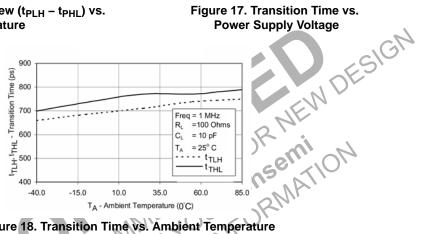


Figure 18. Transition Time vs. Ambient Temperature

ORDERING INFORMATION

Part Number	Operating Range Temperature Package	Shipping [†]
FIN1017MX	-40 to +85°C 8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 inch Narrow (Pb-Free, Halide Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



CASE 751EB **ISSUE A DATE 24 AUG 2017** ·4.90±0.10 → -0.65(0.635)В 6.00±0.20 5.60 3.90±0.10 PIN ONE **INDICATOR** 1.27 1.27 0.25(M) LAND PATTERN RECOMMENDATION В SEE DETAIL A 0.175±0.075 0.22±0.03 С 1.75 MAX 0.10 0.42±0.09 OPTION A - BEVEL EDGE $(0.43) \times 45^{\circ}$ R0.10 GAGE PLANE OPTION B - NO BEVEL EDGE R0.10-0.25 NOTES: A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA. B) ALL DIMENSIONS ARE IN MILLIMETERS. **SEATING PLANE** C) DIMENSIONS DO NOT INCLUDE MOLD 0.65±0.25 FLASH OR BURRS. D) LANDPATTERN STANDARD: SOIC127P600X175-8M (1.04)**DETAIL** À SCALE: 2:1 Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DOCUMENT NUMBER:** 98AON13735G

SOIC8

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

DESCRIPTION:

SOIC8

PAGE 1 OF 1

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales